SPECIFICATION

In the specification, please amend paragraphs [0031], [0032] and [0035] as follows.

[0031] Figure 4 illustrates one cell layout 252 containing two design elements 254 and 258 and two port instances 256 and 260, prior to asymmetric scaling as disclosed herein. Design element 254 is a transistor, for example, and is shown connected to port instance 256. Design element 258 is also a transistor, for example, that is rotated by 90 degrees (relative to design element 254) and connected to port instance 260. Cell layout 252 is, for example, constructed utilizing first fabrication process 126, figure 1. Port instance 256 is located at a position X1, Y1 within cell layout 252. Port instance 260 is located at a position [X1] X2, Y1 within cell layout 252. Design element 258 has a width W1 and a height H1, as shown.

[0032] Figure 4 further illustrates cell layout 272 that represents cell layout 252 after symmetrical scaling by a scale factor of 0.5. Accordingly, design element 274 represents design element 254 scaled by a factor of 0.5; design element 278 represents design element 258 scaled by a factor of 0.5; design element 274 connects to port instance 276, which represents port instance 256; design element 278 connects to port instance 280, which represent port instance 260; port instance 276 is located at a position X4, Y2 within cell layout [172] 272; and port instance 280 is located at position X3, Y2, within cell layout 272. Design element 278 has a width W2 and a height H2. With the 0.5 scaling factor: X3 = X1 * 0.5; X4 = X2 * 0.5; Y2 = Y1 * 0.5; W2 = W1 * 0.5; and H2 = H1 * 0.5. However, if second design rules 132 do not allow for transistor rotation, for example, the orientation of design element 278 is not permitted in second layout 124.

[0035] In the following example, figures 5-10 show a poly layer 300, a metal 1 layer, a metal 2 layer , a metal 3 layer, a metal 4 layer of an exemplary second circuit design 122. In figure 5, poly layer 300 is shown with an exemplary layout grid 301 associated with an exemplary second fabrication process 128. Poly layer 300 is also shown with five exemplary design elements 302, 304, 306, 308 and 310, representing components (e.g., capacitors, resistors, transistors, etc.) of the exemplary second circuit design. Design element 310, in this example, is a high power component utilizing a via array 330, figure 6, which connects to a power trace 358, figure 9. Figure 6 is also shown with grid 301; it further shows connections to poly layer 300, figure 5. Specifically, metal 1 layer includes contacts 312 and 314 that connect to design element 306, contacts 316 and 318 that connect to design element

308, contacts 320, 322 and 324 of a via array 330 that connect power to design element 310, and contacts 326 and 328 that connect to design elements 302 and 304, respectively.